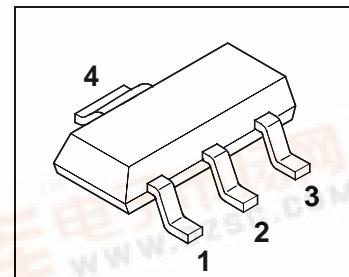


**SIEMENS****BSP 365****MiniSmart**

- High-side switch
- Short-circuit protection
- Overtemperature protection with hysteresis
- Overload protection
- Overvoltage protection
- Reverse battery protection<sup>1)</sup>
- Switching inductive load
- Clamp of negative output voltage with inductive loads
- Maximum current internally limited

Package: SOT 223



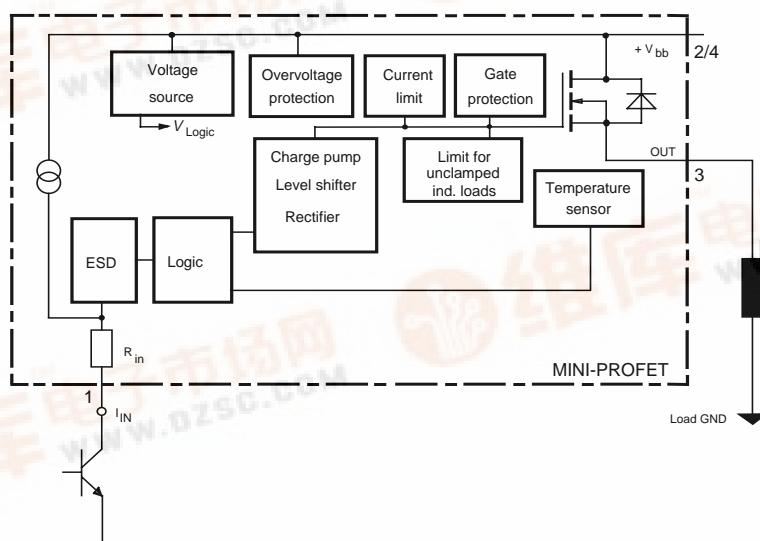
Type	Ordering code
BSP 365	Q67050-M1

**Pins:**

1	2	3	4
IN	$V_{bb}$	OUT	$V_{bb}$

**Maximum Ratings**

Parameter	Symbol	Values	Unit
Supply voltage	$V_{bb}$	65	V
Load current	$I_L$	$I_{L(SC)}$	A
Maximum current through input pin (DC) see internal circuit diagram	$I_{IN}$	$\pm 15$	mA
Inductive load switch-off energy dissipation	$E_{AS}$	5	mJ
Operating temperature range	$T_j$	-40 ... +150	°C
Storage temperature range	$T_{stg}$	-55 ... +150	
Max. power dissipation (DC) <sup>2)</sup>	$P_{tot}$	1.7	W
Thermal resistance chip - soldering point: chip - ambient: <sup>2)</sup>	$R_{thJS}$	17	K/W
	$R_{thJA}$	72	

<sup>1)</sup> For 12 V applications only. Reverse load current only limited by connected load.<sup>2)</sup> BSP 365 on epoxy pcb 40 mm x 40 mm x 1.5 mm with 6 cm<sup>2</sup> copper area for  $V_{bb}$  connection

**Electrical Characteristics**

Parameter and Conditions at $T_j = 25^\circ\text{C}$ , $V_{bb} = 24\text{ V}$ unless otherwise specified	Symbol	Values			Unit
		min	typ	max	

**Load Switching Capabilities and Characteristics**

On-state resistance (pin 2 to 3) $I_L = 100\text{ mA}$ , pin 1 = GND $T_j = 25^\circ\text{C}$ $T_j = 150^\circ\text{C}$ $I_L = 50\text{ mA}$ , $V_{bb} = 4,9\text{ V}$ , $T_j = 25^\circ\text{C}$	$R_{ON}$	-- -- --	4 8 --	5 10 15	$\Omega$
Nominal load current (pin 2 to 3) ISO Standard: $V_{ON} = V_{bb} - V_{OUT} = 0.5\text{ V}$ $T_S = 85^\circ\text{C}$	$I_{L(\text{ISO})}$	0.07	--	--	A
Turn-on time to 90% $V_{OUT}$	$t_{on}$	--	60	100	$\mu\text{s}$
Turn-off time to 10% $V_{OUT}$	$t_{off}$	--	70	100	
$R_L = 270\ \Omega$					
Slew rate on 10 to 30% $V_{OUT}$ , $R_L = 270\ \Omega$	$dV/dt_{on}$	--	4	6	$\text{V}/\mu\text{s}$
Slew rate off 70 to 40% $V_{OUT}$ , $R_L = 270\ \Omega$	$-dV/dt_{off}$	--	2	6	

**Input**

OFF state input current $R_L = 270\ \Omega$ , $V_{OUT} \leq 0,1\text{V}$	$T_j = -40...+150^\circ\text{C}$	$I_{IN(\text{off})}$	--	--	0.05	mA
ON state input current, (pin 1 grounded) <sup>3)</sup>	$T_j = -40...+150^\circ\text{C}$	$I_{IN(\text{on})}$	--	0.35	1	mA

**Operating Parameters**

Operating voltage (pin 1 grounded) <sup>4)</sup> $T_j = -40...+150^\circ\text{C}$		$V_{bb(\text{on})}$	4.9	--	60	V
Leakage current (pin 2 to 3, pin 1 open) $T_j = -40...+150^\circ\text{C}$ $V_{bb} = 60\text{ V}$ , $T_j = -40...+150^\circ\text{C}$		$I_{bb(\text{off})}$	-- --	1.2 --	10 60	$\mu\text{A}$

<sup>3)</sup> Driver circuit must be capable to drive currents >1mA.<sup>4)</sup> Below  $V_{bb}=4.5\text{ V}$  typ. without chargepump,  $V_{out} \approx V_{bb} - 2\text{ V}$

Parameter and Conditions at $T_j = 25^\circ\text{C}$ , $V_{bb} = 24\text{V}$ unless otherwise specified	Symbol	Values			Unit
		min	typ	max	

**Protection Functions**

Current limit (pin 2 to 3) <sup>5)</sup> $T_j = 25^\circ\text{C}$ $T_j = -40\ldots+150^\circ$	$I_{L(\text{SC})}$	0.2	0.5	1	A
Thermal overload trip temperature	$T_{jt}$	150	--	--	$^\circ\text{C}$
Thermal hysteresis	$\Delta T_{jt}$	--	10	--	K
Ovvoltage protection $T_j = -40\ldots+150^\circ\text{C}$	$V_{bb(\text{AZ})}$	65	72	--	V
Output clamp (ind. load switch off) at $V_{\text{OUT}} = V_{bb} - V_{ON(CL)}$	$V_{ON(CL)}$	--	72	--	V
Inductive load switch-off energy dissipation <sup>6)</sup>	$E_{AS}$	--	--	5	mJ
Reverse battery resistor (pin 1 to 2)	$R_{IN}$	--	1	--	k $\Omega$

**Reverse Diode**

Continous reverse drain current $T_j = 25^\circ\text{C}$	$I_S$	--	--	0.2	A
Pulsed reverse drain current $T_j = 25^\circ\text{C}$	$I_{SM}$	--	--	0.8	A
Diode forward on voltage $I_F = 0.2\text{ A}$ , $I_{IN} = \leq 0.05\text{ mA}$	$V_{SD}$	--	0.9	1.2	V

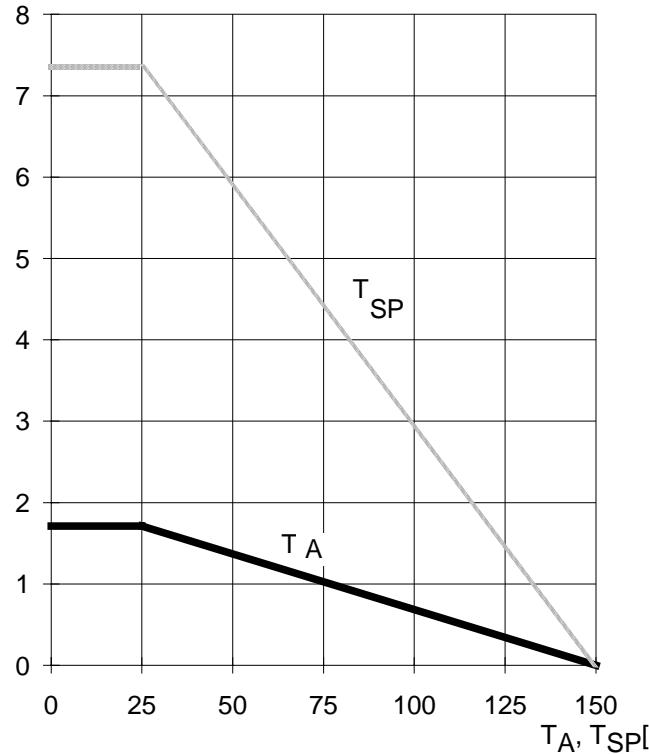
<sup>5)</sup> load current limits onset at  $I_L * R_{on}$  approx. 1V  
short circuit protection: combination of current limit and thermal overload switch off

<sup>6)</sup> while demagnetizing load inductance, dissipated energy is  $E_{AS} = \int (V_{ON(CL)} * i_L(t)) dt$ ,  
approx.  $E_{AS} = 1/2 * L * I_L^2 * (\frac{V_{ON(CL)}}{V_{ON(CL)} - V_{bb}})$

**Max allowable power dissipation**

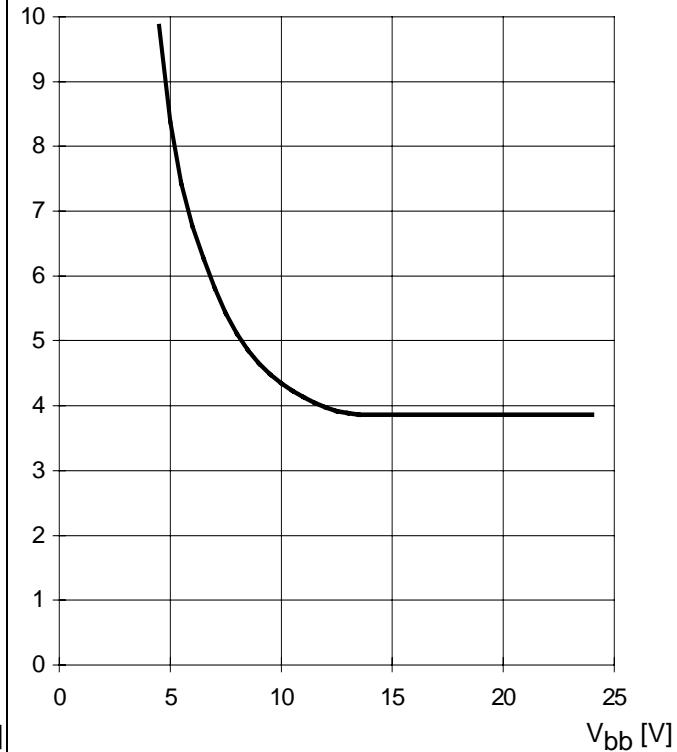
$$P_{\text{tot}} = f(T_A, T_{SP})$$

$P_{\text{tot}}$  [W]

**Typ. on state resistance (V<sub>bb</sub>- pin to OUT pin)**

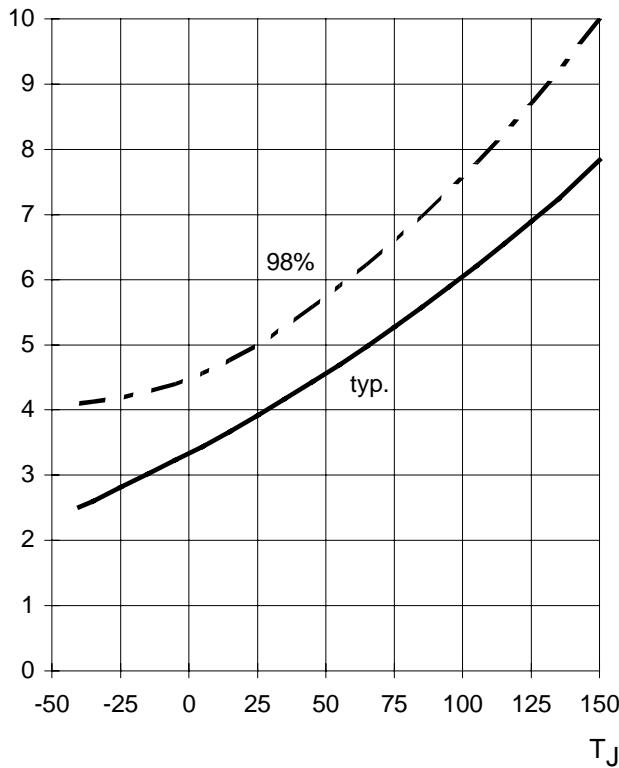
$$R_{ON} = f(V_{bb}); I_L = 70 \text{ mA}; T_j = 25^\circ\text{C}$$

R<sub>ON</sub> [Ω]

**On state resistance (V<sub>bb</sub>- pin to OUT pin)**

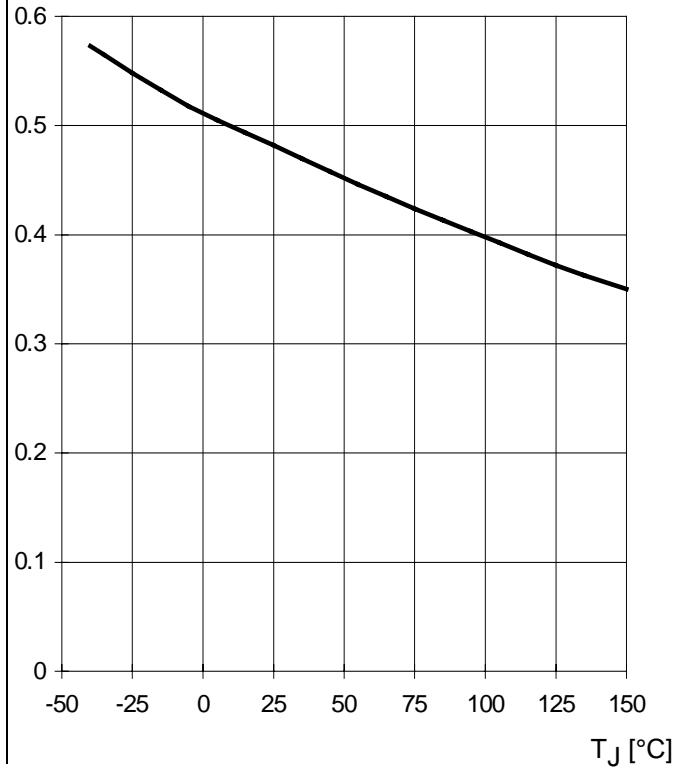
$$R_{ON} = f(T_j); V_{bb} = 13.5 \text{ V}; I_L = 70 \text{ mA}$$

R<sub>ON</sub> [Ω]

**Typ. short circuit current**

$$I_{L(SC)} = f(T_j); V_{bb} = 13.5 \text{ V}$$

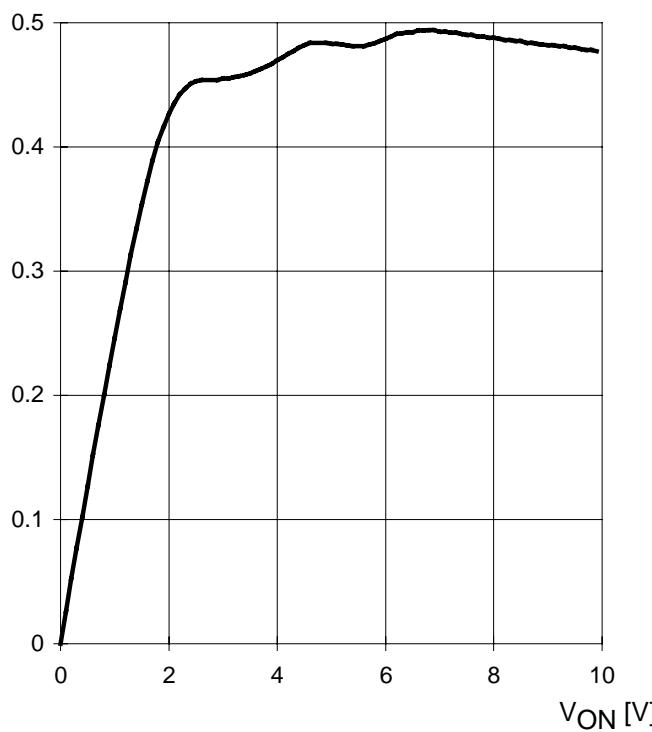
I<sub>LSC</sub> [A]



### Typ. short circuit current

$I_{L(SC)} = f(V_{ON})$ ;  $V_{bb} = 13.5V$ ;  $T_j = 25^\circ C$

$I_{LSC}$  [A]

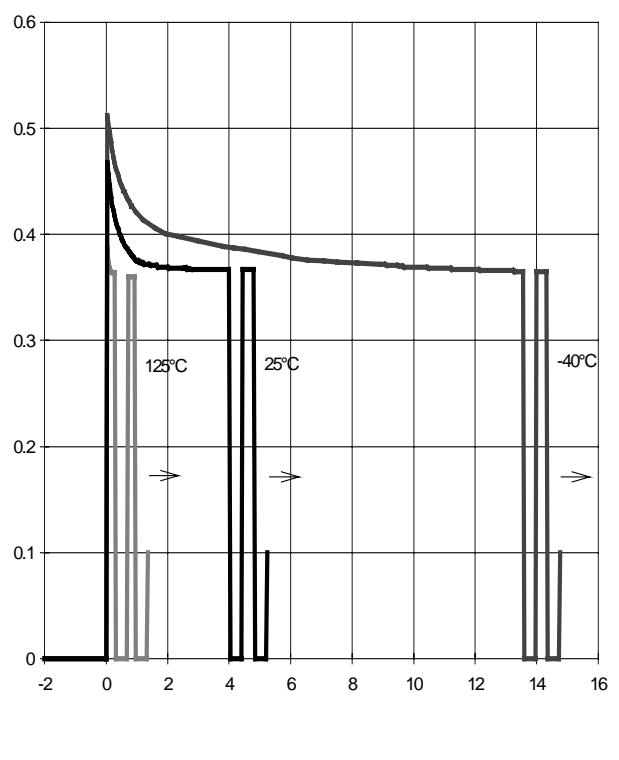


### Typ. short circuit current

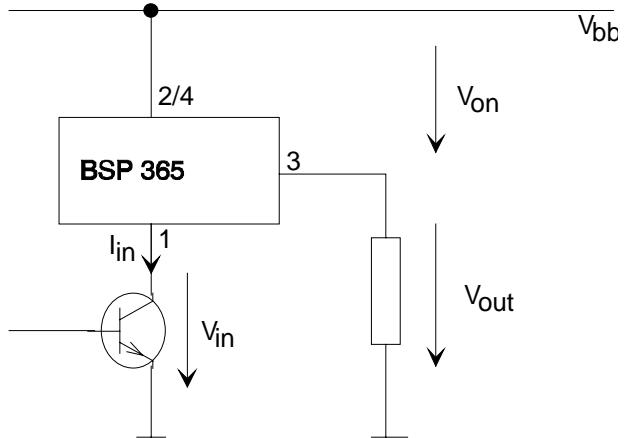
$I_{L(SC)} = f(t)$ ;  $V_{bb} = 13.5V$

no heatsink; Parameter:  $T_{jStart}$

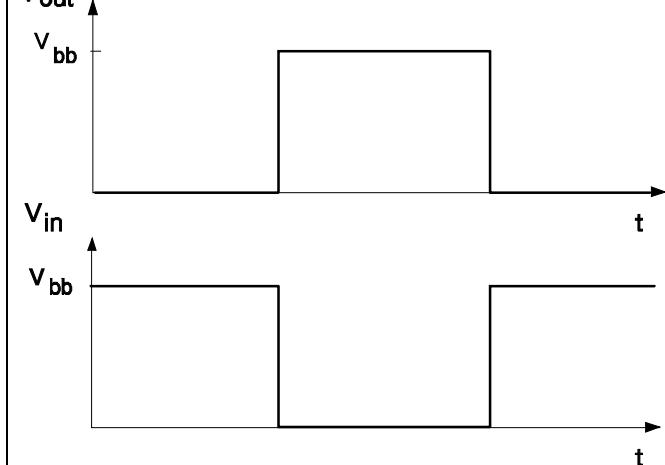
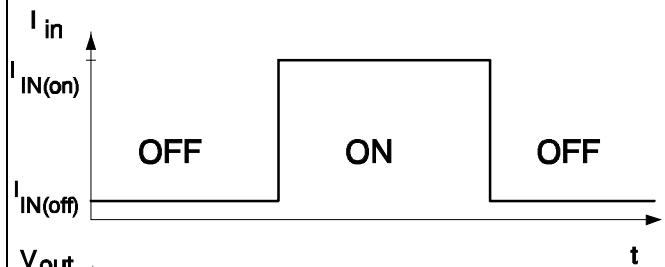
$I_{LSC}$  [A]



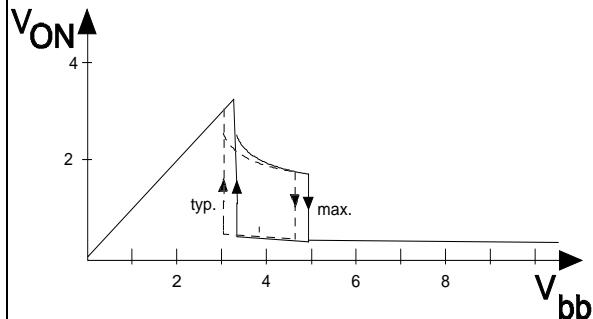
### Test circuit



### Turn on conditions



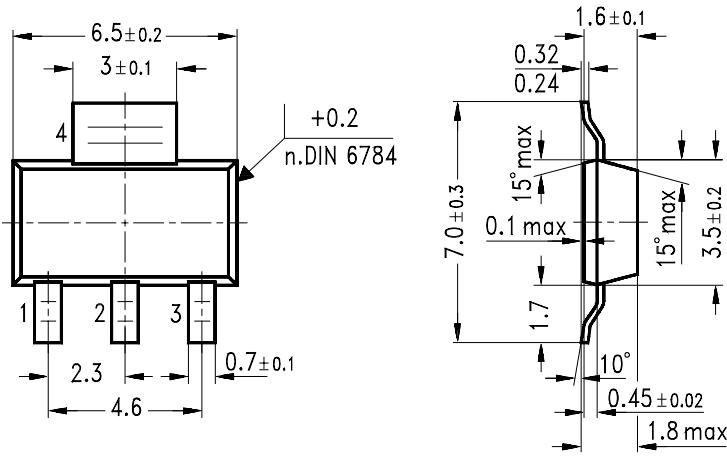
### Chargepump threshold $V_{ON} = f(V_{bb})$



**Package:**

all dimensions in mm.

SOT 223/3:



GPS05560

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